



# In the United States Patent and Trademark Office

Application No.:

09/891,760

Filed:

June 25, 2001

Title:

SELF-ASSEMBLED MICRO ANTI-STICTION STRUCTURE

Applicant:

Chuang-Chia Lin

Examiner:

Tulsidas C. Patel

Art Unit

2839

Express Mail Label # ED 047416814 US

Mailed August 24, 2004

Fremont, CA

## **Information Disclosure Statement**

Commissioner of Patents and Trademarks Washington, District of Columbia 20231

### Dear Sir or Madam:

Attached is a completed Form PTO-1449 and copies of the pertinent parts of the references cited thereon.

It is requested that the document(s) on the enclosed form be made of record. As provided for by 37 CFR 1.97(g) and (h), no inference should be made that the information and references cited are prior art merely because they are in this statement and no representation is being made that a search has been conducted or that this statement encompasses all the possible relevant information.

It is requested that the document(s) on the enclosed form be made of record.

# Part I (Authority)

This statement is filed pursuant to:

( ) 37 C.F.R. § 1.97(b).

> This information disclosure statement is filed either (1) within three months of the filing date of the national applications; (2) within three months of the date of entry of the national stage as set forth in 37 C.F.R. § 1.491 in an international application; (3) before the mailing date of a first office action on the merits; or (4) before the mailing of a first Office action after the filing of a request for continued examination under §1.114, whichever event occurs last.

Accordingly, this information disclosure statement requires no fee and no certification.

(X) 37 C.F.R. § 1.97(c).

This information disclosure statement is filed after the period specified in 37 C.F.R. § 1.97(b), but before the mailing date of either (1) a final action under 37 C.F.R. § 1.113 or (2) a notice of allowance under 37 C.F.R. § 1.311.

Accordingly, this information disclosure statement requires either the fee specified in 37 C.F.R. § 1.17(p) for submission of an information disclosure statement under 37 C.F.R. § 1.97(c) (\$180), or a certification according to 37 C.F.R. § 1.97(e).

This information disclosure statement is filed after the period specified in 37 C.F.R. § 1.97(c).

Accordingly, this information disclosure statement requires the petition fee specified in 37 C.F.R. § 1.17(p) to consider an information disclosure statement under 37 C.F.R. § 1.97(d) (\$180) and a certification according to 37 C.F.R. § 1.97(e).

Conditional Petition

It is respectfully requested that this information disclosure statement be considered, good cause being presented in Part III herein (certification). Please treat this paper as the required petition.

If this statement crosses in the mail with an office action, or is otherwise not in the indicated category of 37 C.F.R. § 1.97, it is respectfully requested that this statement be treated in the next appropriate category and made of record.

है record.

disclos	sure stat	To the extent required, please treat this paper as a conditional petition for acceptance of the information ement.  Part II (Payment)								
A chec	ck is end	closed as indicated: NUS 2 1 7004 \$								
	( )	No fee is due.								
•	(X)	The fee specified in 37 C.F.R. § 1.17(p) for submission of an information disclosure statement ur 37 C.F.R. § 1.97(c) is enclosed (\$180).								
	( )	The petition fee specified in 37 C.F.R. § 1.17(p) to consider an information disclosure statement under 37 C.F.R. § 1.97(d) is enclosed (\$180).								
D	27	Part III (Certification)								
Pursua	int to 37	C.F.R. § 1.97(e), I certify:								
	<b>(X)</b>	No certification is necessary.								
•	() (1) Each item of information contained in the information disclosure statement was cited i communication from a foreign patent office in a counterpart foreign application not more than the months prior to the filing of the statement.									
•		() The "communication from a foreign patent office" referred to in the certification is an International Search Report, possibly issued by the U.S. Patent and Trademark Office in its capacity as an International Search Authority or International Preliminary Examining Authority.								
		() The "counterpart foreign application" referred to in the certification corresponds to an ancestor or descendent application of the application for which this information disclosure statement is filed.								
	()	(2) No item of information contained in the information disclosure statement was cite communication from a foreign patent office in a counterpart foreign application, or, to my knowled making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c), more than months prior to the filing of the statement.								
		Part IV (Additional Statement)								
An add	litional s	statement regarding these items of information ( ) is, (X) is not, enclosed.								
	(X) Co	pies of the cited art references are enclosed,								
		opies of the cited art references are of record in parent application Serial No d will be provided if the Examiner deems it convenient.								
	( ) Co U.S	pies of the cited art references are not required under 37 CFR 1.98(a)(2)(i) because they are S. Patents and/or U.S. Patent Publications and								
	( )	the present application was filed after June 30, 2003, or								
	( )	the present application is an international application that entered the national stage under 35 USC 371 after June 30, 2003.								
Dated:	8/0	Respectfully submitted,  Joshua D. Isenberg  Reg. No. 41,088								

Reg. No. 41,088 204 Castro Lane Fremont, CA 94539 tel: (510) 896-8328 fax: (510) 360-9656

FORM PT	`O-1	449U.S. DEPARTM	CE	ATTY. DOCKET NO. ONX-121			SERIAL NO. 09/891,760					
LIST		PRIOR ART CITES Use several sheets if		ICANT		APPLICANT Chuang-Chia	Lin					
OIP E	3				FILING DATE June 25, 2001		GROUP <b>2839</b>					
Alfo 2 4 2004 g U.S. PATENT DOCUMENTS												
EXAMINER INITIAL TRAU	DOCUMENT DATE NUMBER		NAME		CLASS	SUBCLASS		FILING DATE IF APPROPRIATE				
	A	6,523,961	2/25/2003	Ilkov et a	ıl.		353	99		12/7/2000		
	В	6498,870	12/24/2002	Wu et al.			385	18		4/20/1998		
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• E 5,411,769			5/2/1995	Hornbeck 427			427	534		9/29/1993		
			FOREIG	N PATE	NT	<b>DOCUMENTS</b>						
		DOCUMENT NUMBER	DATE		CO	UNTRY	CLASS	SUBCLASS		TRANSLATION		
										YES NO		
		OTHER PRIOR	R ART (Incl	uding Au	tho	r. Title. Date. Per	rtinent P	ages. E	tc.)			
OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)  R. Legtenberg et al., "Stiction of surface micromachined structures after rinsing and drying: model and										odel and		
	investigation of adhesion mechanisms", Sensors and Actuators A, 43, pp 230-238, 1994  G H. Guckel et al, "Fabrication of Micromechanical Devices from Polysilicon Films with Smooth Surfaces", Sensors and Actuators, 20, pp 117-122 (1989)											
	H R. Alley et al, "The Effect of Release-Etch Processing on Surface Microstructure Stiction", Proc. IEEE Solid-											
	State Sensor & Actuator Workshop, Hilton Head Island, S.C., pp. 202-207 (1992)  D. Kobayashi et al., "An Integrated Lateral Tunneling Unit" Proc. IEEE Micro Electro Mechanical Systems,											
	Travemunde Germany, pp 214-219, (1992)  J N. Takeshima et al. Proc. Int. Conf. Solid-State Sensors & Actuators (Transducers '91), San Francisco, CA, pp.											
	63-66, (1991, IEEE, New York))  K C. Mastrangelo and C. Hsu, "Mechanical Stability and Adhesion of Microstructures Under Capillary Forces –											
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	L C. Mastrangelo and C. Hsu, "Mechanical Stability and Adhesion of Microstructures Under Capillary Forces – Part II: Experiments" Journal of Microelectromechanical Systems, Vol. 2, No. 1 (March 1993) pp. 44-55											
EXAMIN	ER			D	AT	E CONSIDERI	ED					

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.